

* does not represent actual color

SNK60-HXP Form-In-Place

A heat-cure, silver/copper-filled silicone elastomer Form-In-Place gasket material.

Laird Technologies introduces its newest line of FIP products—EMI Sentry. These Form-In-Place pastes are extremely fast curing with reliable shielding effectiveness and strength.

Laird Technologies' Form-In-Place is an automated system for dispensing conductive elastomer EMI shielding and grounding gaskets onto metal or plastic substrates. This product is particularly ideal for basestations, PDAs, PC cards, radios, mobile phones, as well as many other cast or plastic enclosures and packaged electronic assemblies.

TYPICAL VALUES

	TEST METHOD	UNITS	SNK60-HXP
Elastomer			Silicone
Filler			Silver/Copper
ELECTRICAL PROPERTIES			
Volume Resistivity		ohm-cm	0.004
Shielding Effectiveness	MIL-DTL-83528C		
200 MHz to 10 GHz	Para. 4.5.12	dB	>90
PHYSICAL PROPERTIES			
Hardness	ASTM D2240	Shore A	60
Tensile Strength	ASTM D412	kPa	2500
Tensile Elongation	ASTM D412	%	130
Density (cured)	ASTM D792	g/cm ³	3.1
Density (uncured)	LT-FIP-CLE-09	g/cm ³	3.1
Compression Set	ASTM D395	%	10
Adhesion Strength (AI)	LT-FIP-CLE-03	N/cm ²	200
Compression-Deflection (a)	LT-FIP-CLE-07		
at 20% compression		lb/in	1.5
at 40% compression		lb/in	7.3
Temperature Range		°C	-50°C to 125°C
UL rating	UL-94		V0
CURING REQUIREMENTS			
Cure Conditions		120°C minimum	
Cure Time at 125°C (b)	LT-FIP-CLE-14		1.5 hours

(a) Compression-deflection bead size 0.60 mm (H) x 0.70 mm (W)

(b) Time to effectively cure a bead will necessarily depend on individual conditions, including bead size, shield size and weight, oven capacity, and oven ramp-rates.

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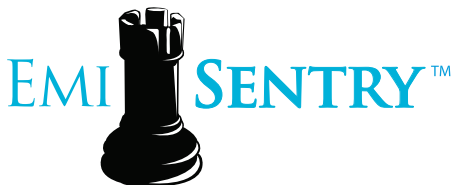
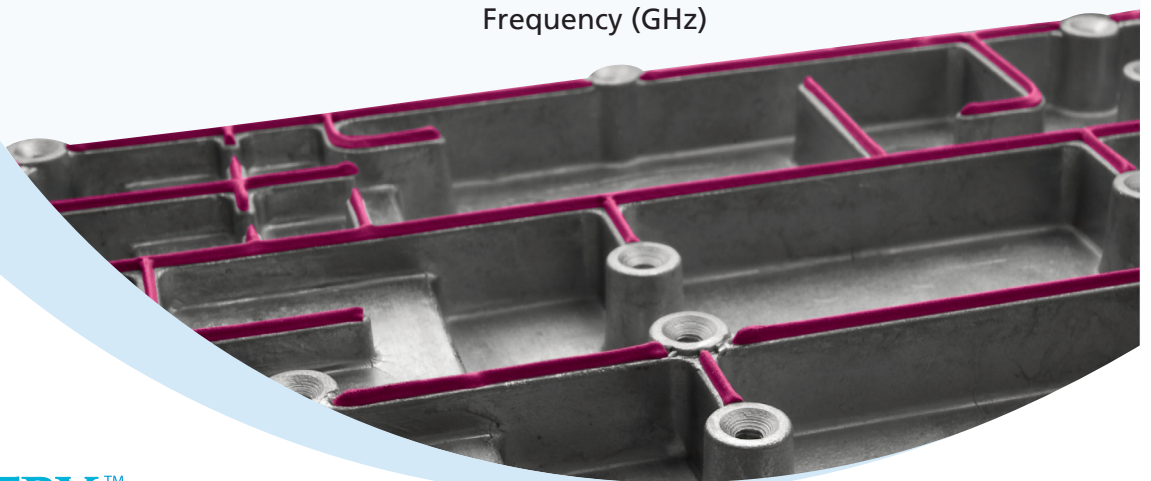
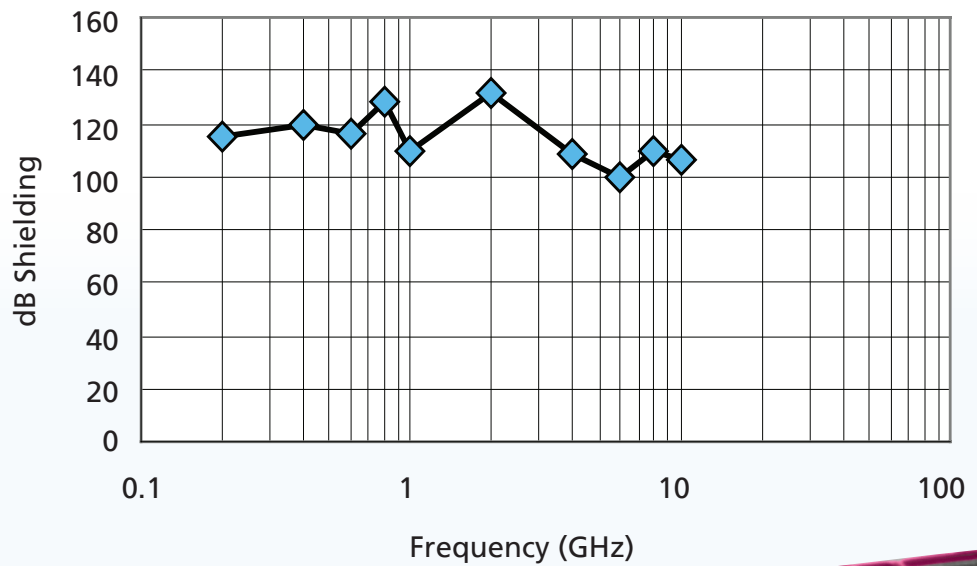


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SNK60-HXP is the heat temperature cured silver/copper paste in the EMI Sentry paste product line. This paste has higher strength and faster curing capabilities. Products in the EMI Sentry line all have superior adhesion strength, strong reliability in low compression sets, as well as heat and humidity resistance.

SNK60-HXP
Shielding Effectiveness (dB)
Preliminary



EMI-DS-FIP-SNK60-HXP 0709

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